

March 2010

BS170 / MMBF170 N-Channel Enhancement Mode Field Effect Transistor

General Description

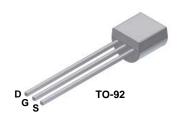
These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 500mA DC. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

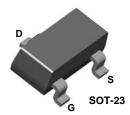
Features

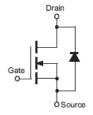
- High density cell design for low R_{DS(ON)}.
- Voltage controlled small signal switch.
- Rugged and reliable.
- High saturation current capability.

BS170

MMBF170







Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	BS170	MMBF170	Units
V _{DSS}	Drain-Source Voltage		V	
V_{DGR}	Drain-Gate Voltage ($R_{GS} \le 1M\Omega$)	(60	V
V _{GSS}	Gate-Source Voltage	±	V	
I _D	Drain Current - Continuous	500	500	mA
	- Pulsed	1200	800	- IIIA
T _J , T _{STG}	Operating and Storage Temperature Range	- 55	°C	
T _L	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds	3	°C	

Thermal Characteristics $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	BS170	MMBF170	Units
P _D	Maximum Power Dissipation Derate above 25°C	830 6.6	300 2.4	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	150	417	°C/W

$\textbf{Electrical Characteristics} \quad \textbf{T}_{A}\text{=}25^{\circ}\text{C unless otherwise noted}$

Symbol	Parameter	Conditions	Type	Min.	Тур.	Max.	Units
OFF CHA	RACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 100 \mu A$	All	60			V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 25V, V_{GS} = 0V$	All			0.5	μΑ
I _{GSSF}	Gate - Body Leakage, Forward	$V_{GS} = 15V$, $V_{DS} = 0V$	All			10	nA
ON CHAR	RACTERISTICS (Notes 1)						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 1mA$	All	8.0	2.1	3	V
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 200mA$	All		1.2	5	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 10V, I_{D} = 200 \text{mA}$	BS170		320		mS
		$V_{DS} \ge 2 V_{DS(on)},$ $I_D = 200 \text{mA}$	MMBF170		320		
Dynamic	Characteristics		1				
C _{iss}	Input Capacitance	$V_{DS} = 10V, V_{GS} = 0V,$	All		24	40	pF
C _{oss}	Output Capacitance	f = 1.0MHz	All		17	30	pF
C _{rss}	Reverse Transfer Capacitance		All		7	10	pF
Switching	Characteristics (Notes 1)				•		
t _{on}	Turn-On Time	$V_{DD} = 25V, I_{D} = 200mA, V_{GS} = 10V, R_{GEN} = 25\Omega$	BS170			10	ns
		$V_{DD} = 25V, I_{D} = 500mA,$ $V_{GS} = 10V, R_{GEN} = 50\Omega$	MMBF170			10	
t _{off}	Turn-Off Time	$V_{DD} = 25V, I_{D} = 200 \text{mA},$ $V_{GS} = 10V, R_{GEN} = 25\Omega$	BS170			10	ns
		$V_{DD} = 25V, I_D = 500 \text{mA},$ $V_{GS} = 10V, R_{GEN} = 50\Omega$	MMBF170			10	

Note:

Ordering Information

Part Number	Package	Package Type	Lead Frame	Pin array
BS170	TO-92	BULK	STRAIGHT	DGS
BS170_D26Z	TO-92	Tape and Reel	FORMING	DGS
BS170_D27Z	TO-92	Tape and Reel	FORMING	DGS
BS170_D74Z	TO-92	AMMO	FORMING	DGS
BS170_D75Z	TO-92	AMMO	FORMING	DGS
MMBF170	SOT-23	Tape and Reel		

^{1.} Pulse Test: Pulse Width $\leq~300\mu s,~Duty~Cycle \leq 2.0\%.$

Typical Electrical Characteristics

BS170 / MMBF170

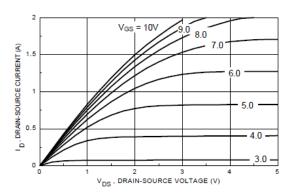


Figure 1. On-Region Characteristics.

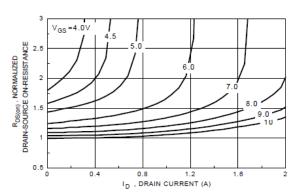


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.

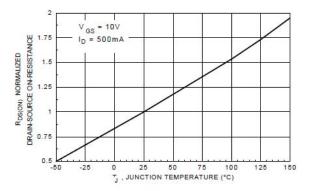


Figure 3. On-Resistance Variation with Temperature.

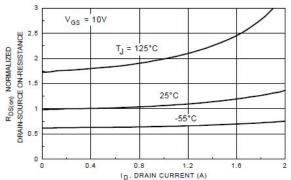


Figure 4. On-Resistance Variation with Drain Current and Temperature.

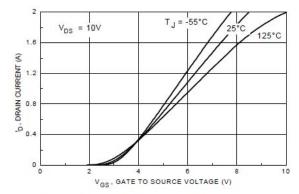


Figure 5. Transfer Characteristics.

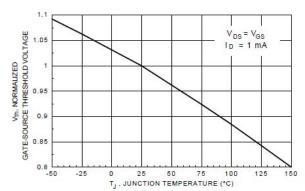


Figure 6. Gate Threshold Variation with Temperature.

Typical Electrical Characteristics (continued)

BS170 / MMBF170

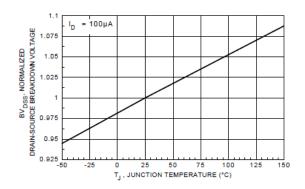


Figure 7. Breakdown Voltage Variation with Temperature.

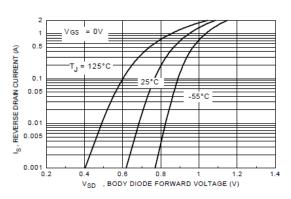


Figure 8. Body Diode Forward Voltage Variation with Current and Temperature.

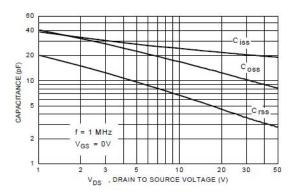


Figure 9. Capacitance Characteristics.

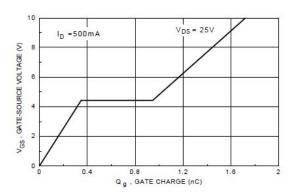


Figure 10. Gate Charge Characteristics.

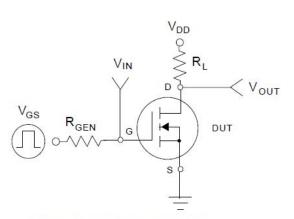


Figure 11. Switching Test Circuit.

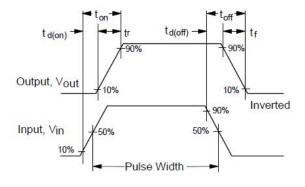
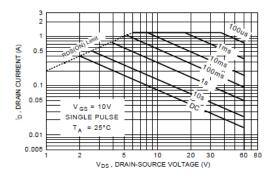


Figure 12. Switching Waveforms.

Typical Electrical Characteristics (continued)



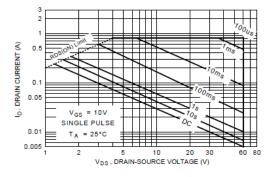


Figure 13. BS170 Maximum Safe Operating Area.

Figure 14. MMBF170 Maximum Safe Operating Area.

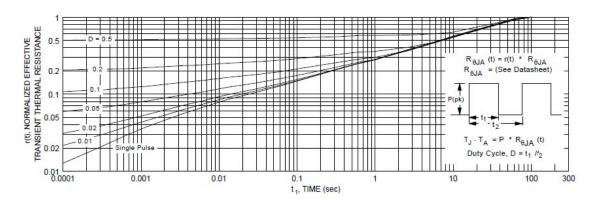


Figure 15. TO-92, BS170 Transient Thermal Response Curve.

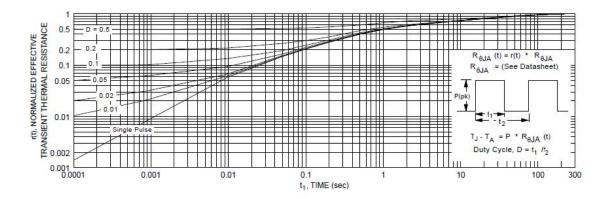
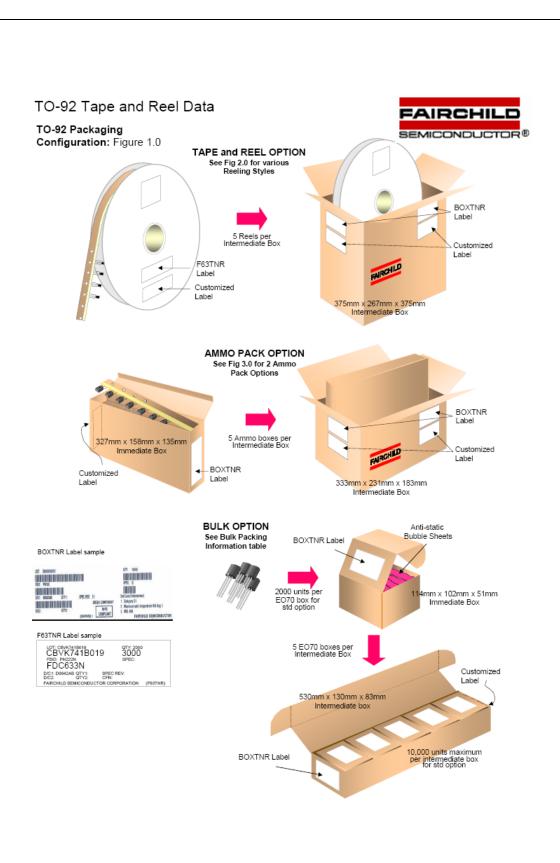


Figure 16. SOT-23, MMBF170 Transient Thermal Response Curve.



TO-92 Tape and Reel Data, continued



TO-92 Packing Information: Figure 2.0

TO-92 TNR/AMMO PACKING INFORMATION TABLE

Packing	Style	Quantity	EOL code
Reel	Α	2,000	D26Z
	В	2,000	D11Z
	С	2,000	D28Z
	D	2,000	D10Z
	E	2,000	D27Z
	F	2,000	D81Z
	G	2,000	D29Z
	Н	2,000	D89Z
Ammo	М	2,000	D74Z
	P	2,000	D75Z

Unit weight = 0.22 gm
Reel weight with components = 1.04 kg
Ammo weight with components = 1.02 kg
Max quantity per intermediate box = 10,000 units

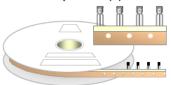
TO-92 BULK PACKING INFORMATION TABLE

EOL CODE /FLOW OPTION	DESCRIPTION	LEADCLIP DIMENSION	MINIMUM ORDER QTY	LEADFORM OULTINE
NO EOL CODE	STRAIGHT LEADS	NO LEAD CLIP	2.0K / BOX	-
J18Z	TO-18 OPTION STD	NO LEAD CLIP	2.0K / BOX	
J35Z	TO-18 OPTION REVERSE	NO LEAD CLIP	2.0K / BOX	
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.5K / BOX	
J60Z	TO-5 OPTION REVERSE	NO LEAD CLIP	1.5K / BOX	
J61Z	IN LINE 0.200 SPACING	NO LEAD CLIP	1.5K / BOX	

TO-92 Tape and Reel Data, continued

TO-92 Reeling Style Configuration: Figure 3.0

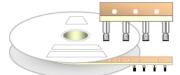
Machine Option "A" (H)



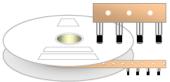
Style "A", D26Z



Style "B", D11Z



Style "C", D28Z



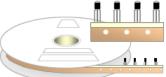
Style "D", D10Z

TO-92 Radial Ammo Packaging Configuration: Figure 4.0

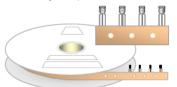




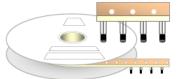
Machine Option "E" (J)



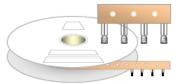
Style "E", D27Z



Style "F", D81Z



Style "G", D29Z



Style "H", D89Z

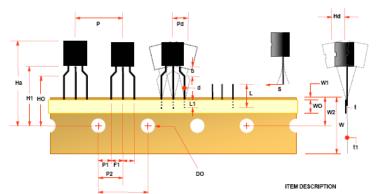


FIRST WIRE OFF IS COLLECTOR ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON TOP

TO-92 Tape and Reel Data, continued

TO-92 Tape and Reel Taping
Dimension Configuration: Figure 5.0





User Direction of Feed

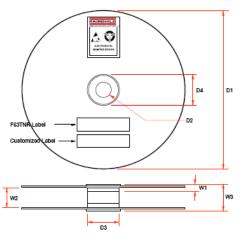
0.098 (max) Base of Package to Lead Bend Component Height Lead Clinch Height 0.928 (+/- 0.025) но 0.630 (+/- 0.020) Component Base Height 0.748 (+/- 0.020) 0.040 (max) 0.031 (max) Component Alignment (side/side) Pd Hd Component Alignment (front/back) Component Pitch Feed Hole Pitch 0.500 (+/- 0.020) РО 0.500 (+/- 0.008) Hole Center to Component Center P2 0.247 (+/- 0.007) 0.104 (+/- 0.010) F1/F2 Lead Spread 0.018 (+0.002, -0.003) Cut Lead Length 0.429 (max) 0.209 (+0.051, -0.052) L1 Taped Lead Length Taped Lead Thickness 0.032 (+/- 0.006) Carrier Tape Thickness tι 0.021 (+/- 0.006) Carrier Tape Width 0.708 (+0.020, -0.019) Hold - down Tape Width wo 0.236 (+/- 0.012) 0.035 (max) Hold - down Tape position 0.360 (+/- 0.025) 0.157 (+0.008, -0.007) DO Sprocket Hole Diamete

SYMBOL

DIMENSION

0.004 (max)

TO-92 Reel Configuration: Figure 6.0



ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Dlameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Dlameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

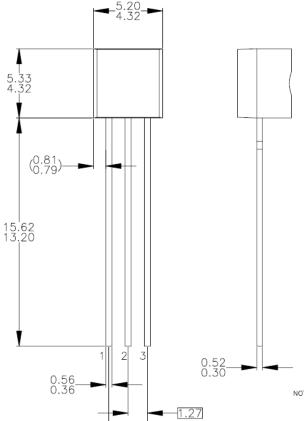
Note: All dimensions are inches

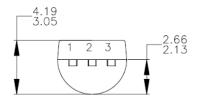
Lead Spring Out

Note : All dimensions are in inches

Mechanical Dimensions (TO-92)

TO-92





2.54

NOTES: UNLESS OTHERWISE SPECIFIED

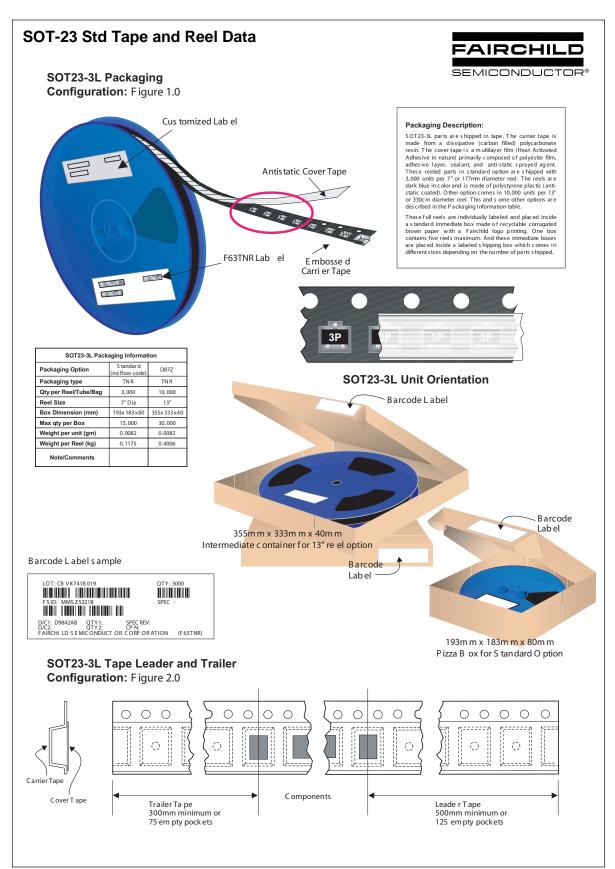
- DRAWING WITH REFERENCE TO JEDEC TO-92 RECOMMENDATIONS. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING CONFORMS TO ASME Y14.5M-1994. TO-92 (92,94,96,97,98) PIN CONFIGURATION:

z		92		94			96			97			98		
<u>a</u>	Р	F	М	Р	F	М	Р	F	М	Р	F	М	Р	F	М
1	Ε	S	S	Ε	S	S	В	D	G	С	G	D	С	G	D
2	В	D	G	С	G	D	Ε	S	S	В	D	G	Ε	S	S
3	С	G	D	В	D	G	С	G	D	Ε	S	S	В	D	G

LEGEND: P - BIPOLAR F - JFET M - DMOS E - EMITTER B - BASE C - COLLECTOR D - DRAIN S - SOURCE G - GATE

- FOR PACKAGE 92, 94, 96, 97 AND 98: PIN CONFIGURATION DRAIN "O" AND SOURCE "S" ARE INTERCHANGEAGLE AT JFET "F" OPTION. DRAWING FILENAME: MKT-ZAO3DREV3. E)

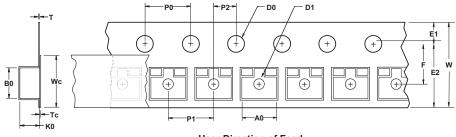
Dimensions in Millimeters





SOT23-3L Embossed Carrier Tape

Configuration: Figure 3.0



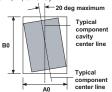
User Direction of Feed	

	Dimensions are in millimeter													
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	т	Wc	Тс
SOT-23 (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

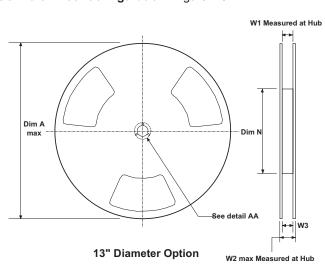


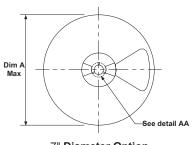
Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

SOT23-3L Reel Configuration: Figure 4.0





7" Diameter Option

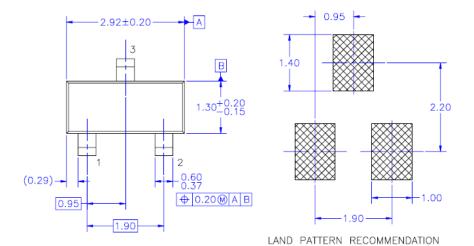
B Min

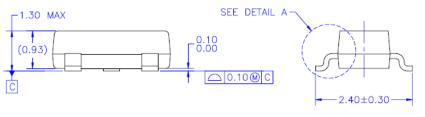
Dim C

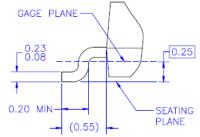
								DETAIL AA	ı
	Dimensions are in inches and millimeters								
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9

Mechanical Dimensions (SOT-23)

SOT-23







DETAIL A

- NOTES: UNLESS OTHERWISE SPECIFIED
 - REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H.
 ALL DIMENSIONS ARE IN MILLIMETERS.
 DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994.
 DRAWING FILE NAME: MAO3DREV9

Dimensions in Millimeters



The Power Franchise®

uwer

franchise

TinyBoost™

TinvBuck™

TinyCalc™

TinyLogic[®]

TINYOPTO™

TinyPower™

TinyPWM™

TinyWire™

TriFault Detect™

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CROSSVOLT™ GTO™ CTL™ IntelliMAX™ Current Transfer Logic™ ISOPLANAR™ DEUXPEED® MegaBuck™

Dual Cool™ MIČROCOUPLER™ EcoSPARK® MicroFET™ EfficientMax™ MicroPak™

® MicroPak2™ MillerDrive™ Fairchild® MotionMax™ Fairchild Semiconductor® Motion-SPM™ FACT Quiet Series™ OptoHiT™ FACT OPTOLOGIC® FAST® OPTOPLANAR®

FETBench™ FlashWriter®* PDP SPM™ FPS™ Power-SPM™ F-PFS™

PowerTrench® PowerXS™

Programmable Active Droop™

QS™ Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™ SPM® STEALTH™ SuperFET™ . SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS™ SyncFET™ Sync-Lock™

GENERAL

TRUECURRENT™* μSerDes™ UHC Ultra FRFET™ UniFET™ VCX™ VisualMax™ XS™

DISCLAIMER

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- 2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

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Product Status	Definition								
Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.								
First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.								
Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.								
Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.								
	Formative / In Design First Production Full Production								

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